

Reliability

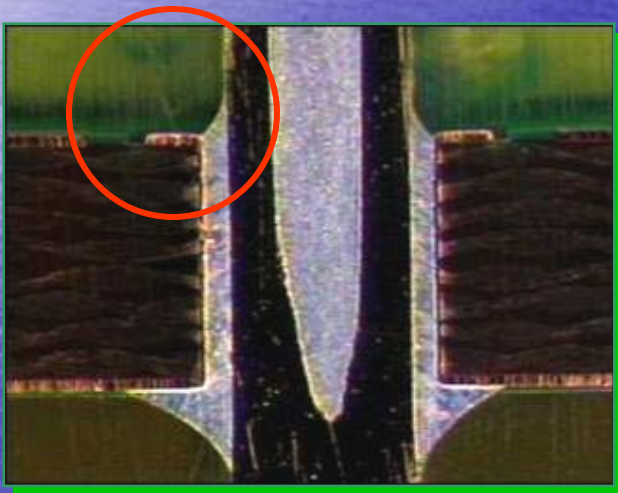
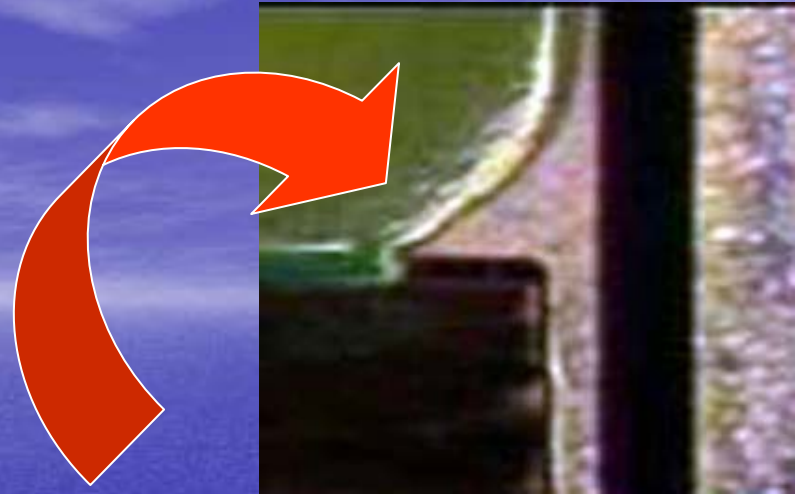
There have been no observations that solder joints produced using MS2™ are of lower quality or reliability

In fact there are observations that solder joints produced using MS2™ are of higher quality

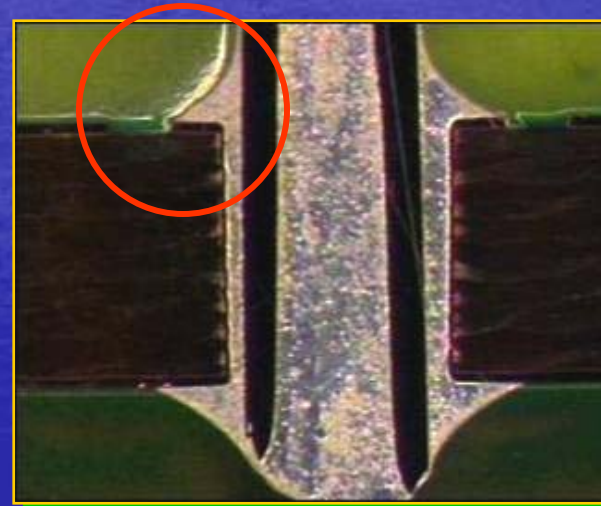
There is now statistical evidence that MS2™ contributes to improved quality and throughput

“The conclusion that can be drawn is that the samples with MS2 have hole fill that is as good or better than without MS2”

Kola Akinade PhD, Scientific Atlanta



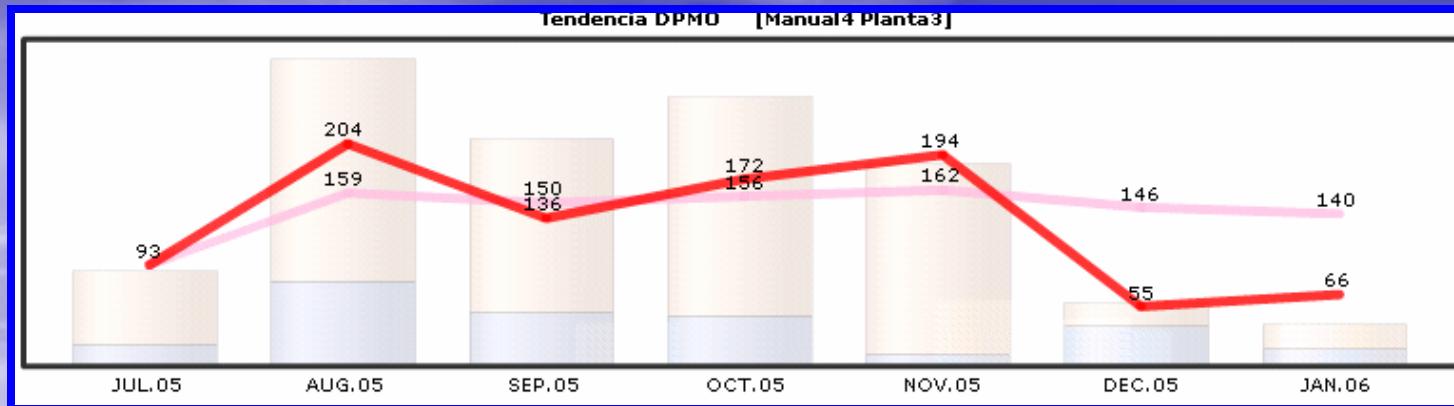
Standard SN/PB Process



Standard SN/PB Process
With Material

Data provided by Scientific Atlanta

P. Kay Metal, MS2



Data provided by Scientific Atlanta

GM PS 593021- Line 4 September 2005)					
Machine	Inspected	Defects	Ofe	DPU	DPMO
Matl	1899	4	0	0.0021	0
MANUAL	1899	22	56970	0.0116	386.17
RADIAL	1899	13	39879	0.0068	325.99
AXIAL	1899	4	66465	0.0021	60.18
W Solder	1899	14	389295	0.0074	35.96
		57	552609		103.1
		Solder defects	14		25.3
GM PS 593021- Line 4 January 2006) using the solution					
Machine	Inspected	Defects	Ofe	DPU	DPMO
MANUAL	2003	16	60090	0.008	266.27
Wave	2003	0	410615	0	0.00
RADIAL	2003	0	42063	0	0.00
AXIAL	2003	0	70105	0	0
Matl	2003	0	0	0	0
		16	582873		27.5
		Solder defects	0		0.0

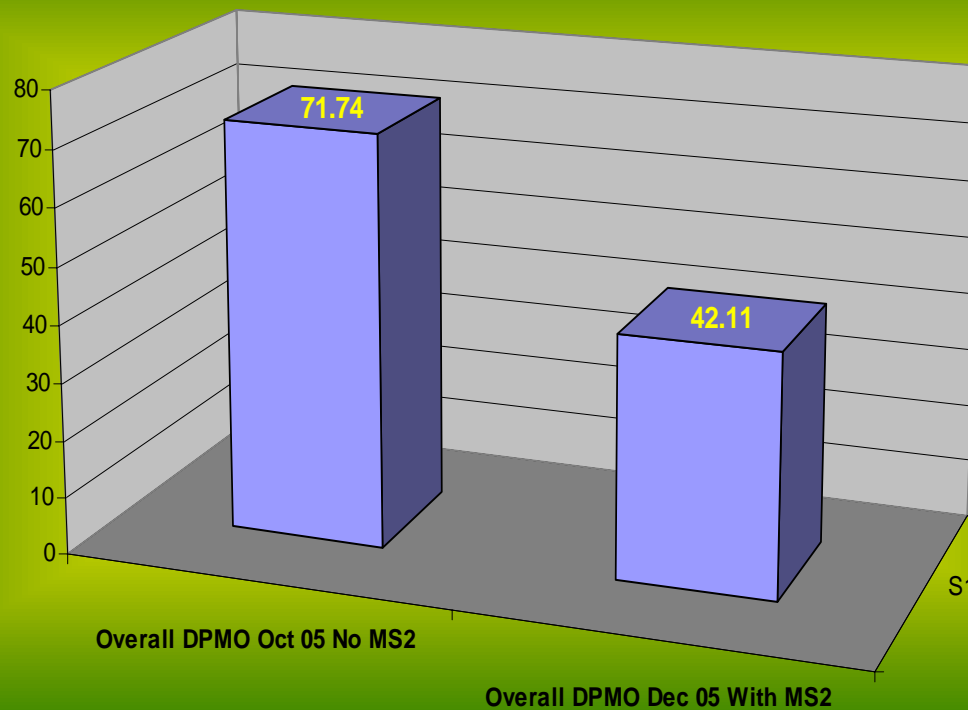
Comparison
75.5 DPMOS Less in General

27.5 DPMOS less for soldering defects

Statistically Valid Month vs. Month Comparison, Same Machine, Full Production

October 2005 Without MS2™ vs. December 2005 With MS2™

Defects Per Million Opportunities



Data provided by
Scientific Atlanta

Statistically Valid Month vs. Month Comparison, Same Machine, Full Production

October 2005 Without MS2™ vs. December 2005 With MS2™

Defects Per Million Opportunities



Solder Related Defects Only

Data provided by
Scientific Atlanta

P. Kay Metal, MS2